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# 2SK3082(L),2SK3082(S)

Silicon N Channel MOS FET  
High Speed Power Switching

# HITACHI

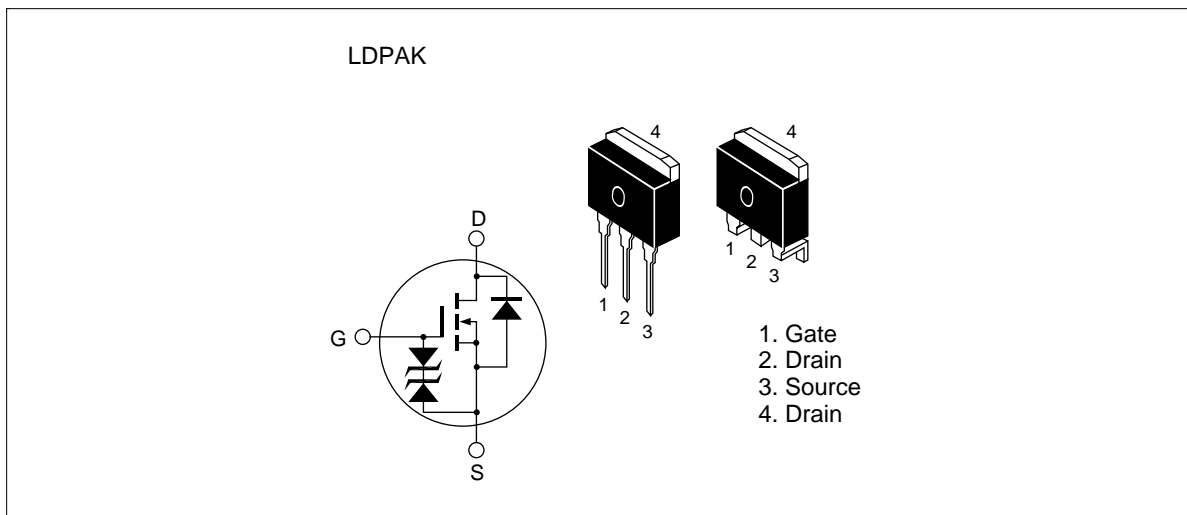
ADE-208-637 (Z)  
2nd. Edition  
May 1998

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## Features

- Low on-resistance  
 $R_{DS(on)} = 0.055 \Omega$  typ.
- High speed switching
- 4V gate drive device can be driven from 5V source

## Outline



## 2SK3082(L),2SK3082(S)

### Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	60	V
Gate to source voltage	$V_{GSS}$	±20	V
Drain current	$I_D$	10	A
Drain peak current	$I_{D(pulse)}$ <sup>Note1</sup>	40	A
Body-drain diode reverse drain current	$I_{DR}$	10	A
Avalanche current	$I_{AP}$ <sup>Note3</sup>	10	A
Avalanche energy	$E_{AR}$ <sup>Note3</sup>	8.5	mJ
Channel dissipation	$P_{ch}$ <sup>Note2</sup>	30	W
Channel temperature	$T_{ch}$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

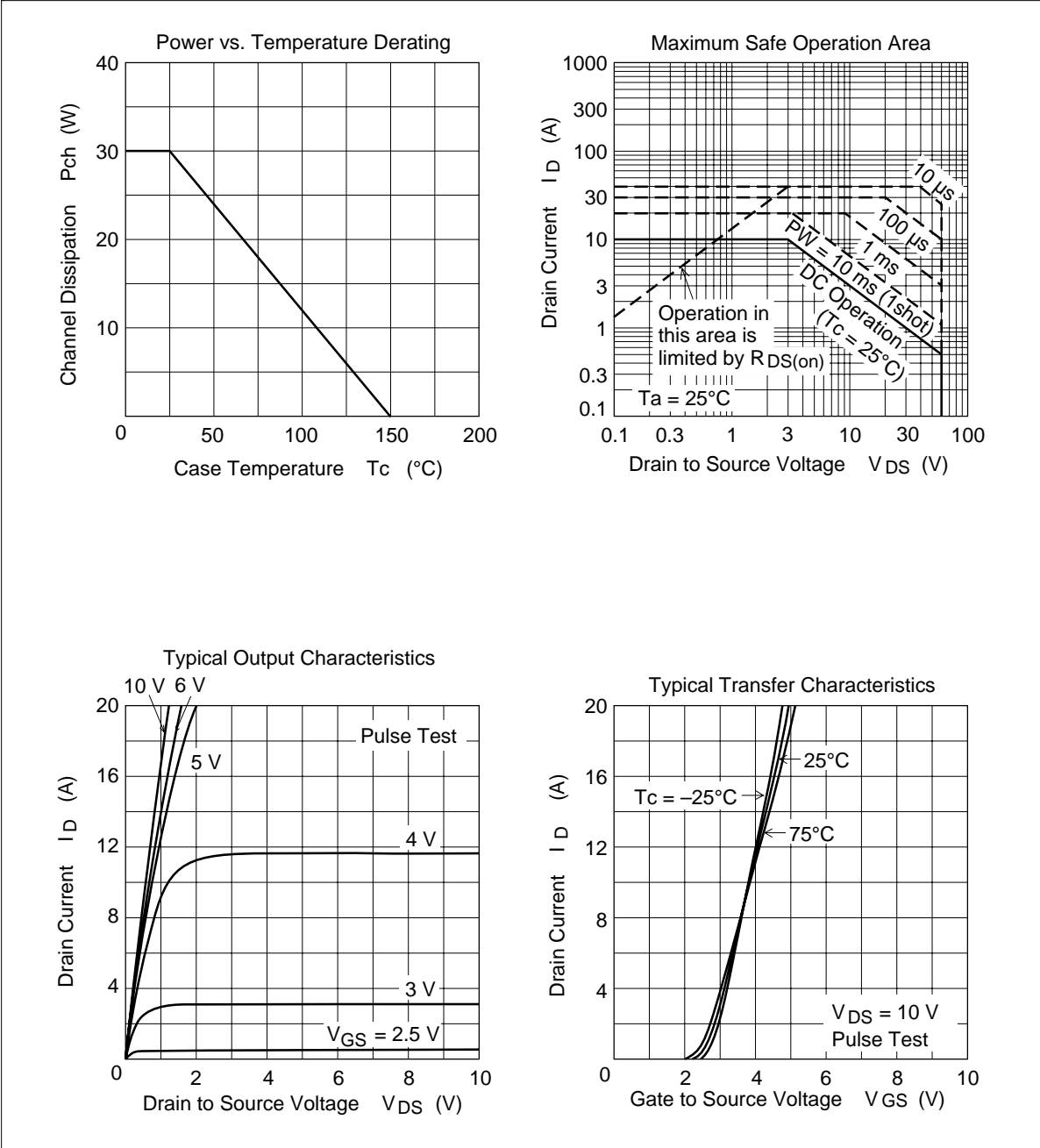
Note: 1.  $PW \leq 10\mu s$ , duty cycle  $\leq 1\%$   
 2. Value at  $T_c = 25^\circ C$   
 3. Value at  $T_{ch} = 25^\circ C$ ,  $R_g \geq 50\Omega$

### Electrical Characteristics (Ta = 25°C)

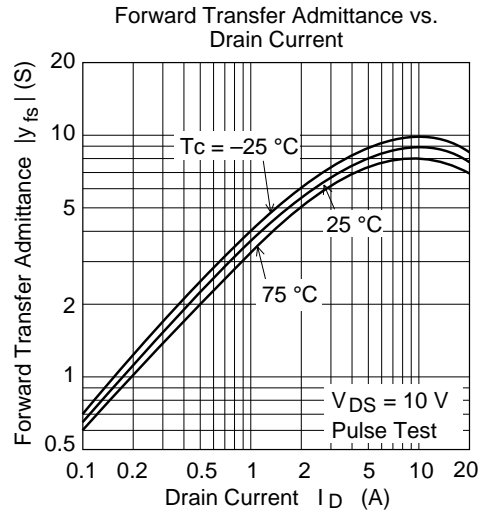
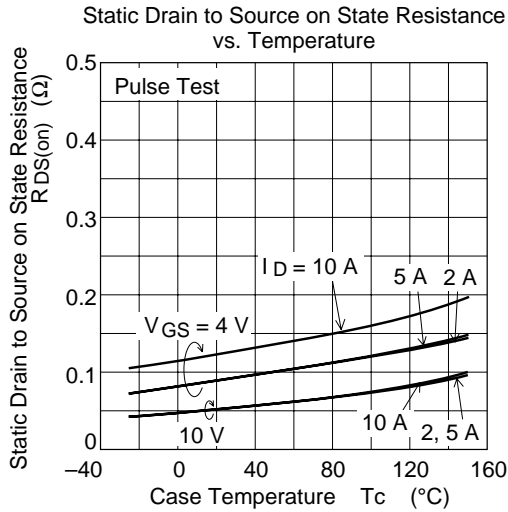
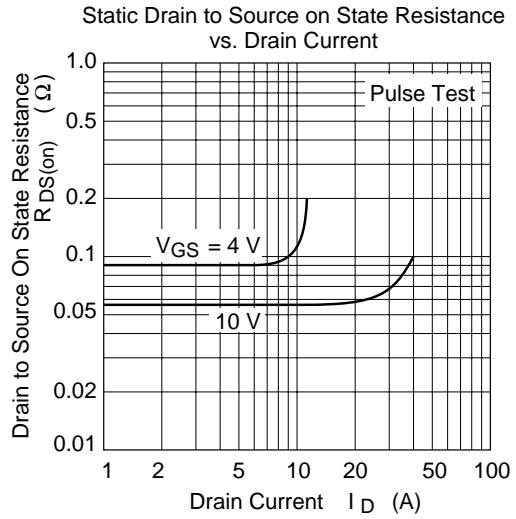
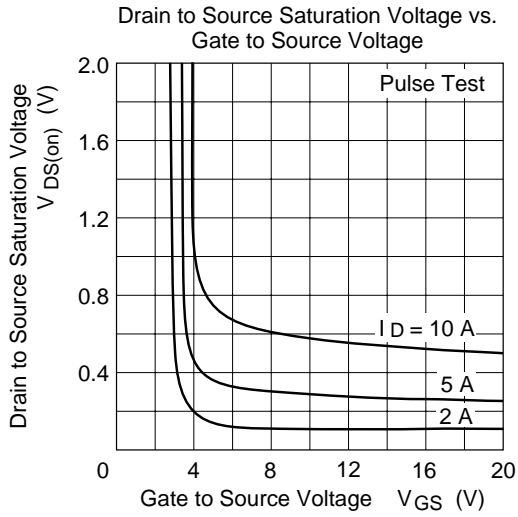
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	$I_D = 10mA$ , $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	$I_G = \pm 100\mu A$ , $V_{DS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	±10	μA	$V_{GS} = \pm 16V$ , $V_{DS} = 0$
Zero gate voltage drain current	$I_{DSS}$	—	—	10	μA	$V_{DS} = 60V$ , $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.5	—	2.5	V	$I_D = 1mA$ , $V_{DS} = 10V$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.055	0.075	Ω	$I_D = 5A$ , $V_{GS} = 10V$ <sup>Note4</sup>
	$R_{DS(on)}$	—	0.090	0.150	Ω	$I_D = 5A$ , $V_{GS} = 4V$ <sup>Note4</sup>
Forward transfer admittance	$ y_{fs} $	5	8	—	S	$I_D = 5A$ , $V_{DS} = 10V$ <sup>Note4</sup>
Input capacitance	$C_{iss}$	—	350	—	pF	$V_{DS} = 10V$
Output capacitance	$C_{oss}$	—	190	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	$C_{rss}$	—	70	—	pF	$f = 1MHz$
Turn-on delay time	$t_{d(on)}$	—	10	—	ns	$I_D = 5A$ , $V_{GS} = 10V$
Rise time	$t_r$	—	55	—	ns	$R_L = 6\Omega$
Turn-off delay time	$t_{d(off)}$	—	60	—	ns	
Fall time	$t_f$	—	70	—	ns	
Body-drain diode forward voltage	$V_{DF}$	—	0.9	—	V	$I_F = 10A$ , $V_{GS} = 0$
Body-drain diode reverse recovery time	$t_{rr}$	—	50	—	ns	$I_F = 10A$ , $V_{GS} = 0$ $diF/dt = 50A/\mu s$

Note: 4. Pulse test

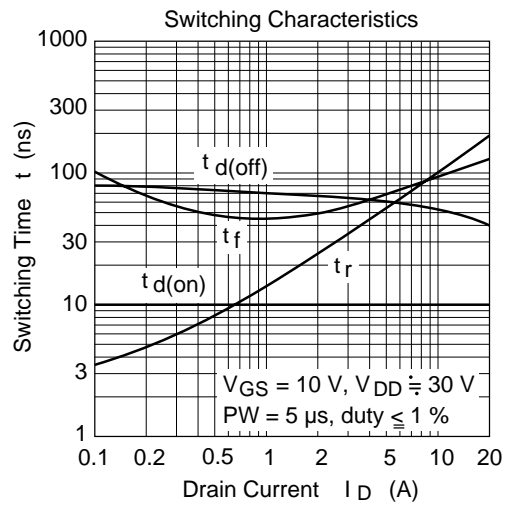
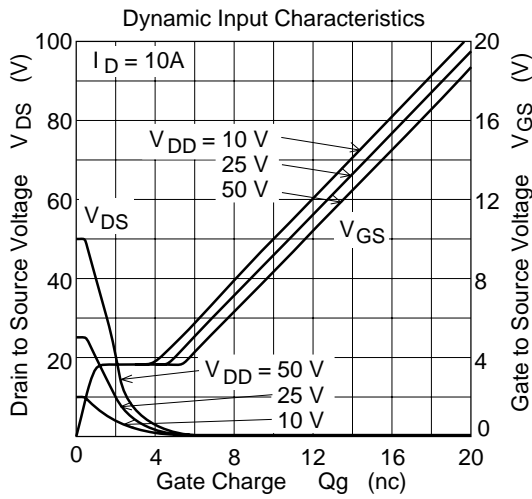
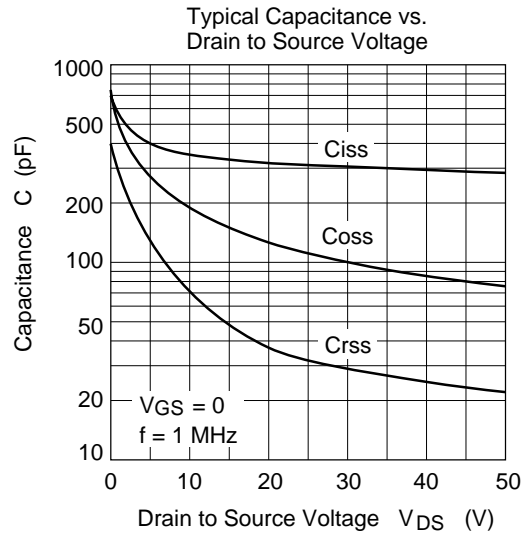
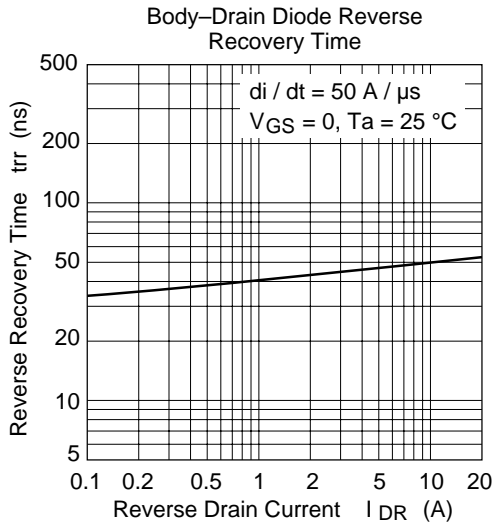
Main Characteristics



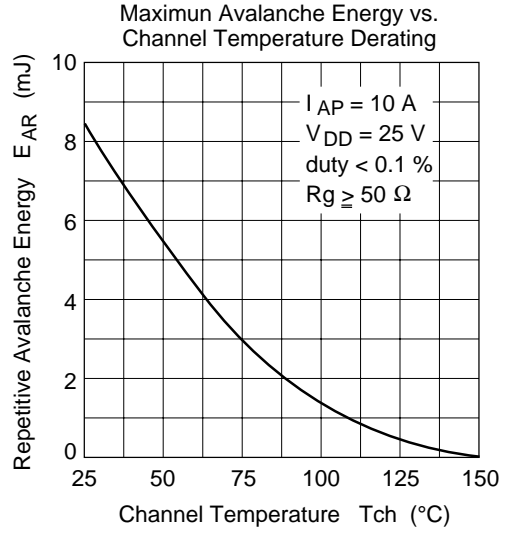
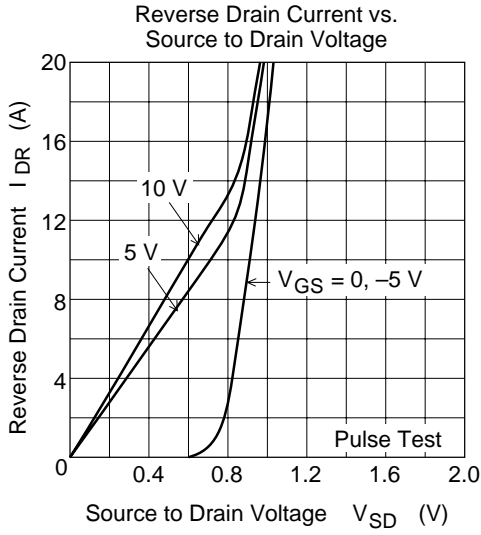
# 2SK3082(L),2SK3082(S)



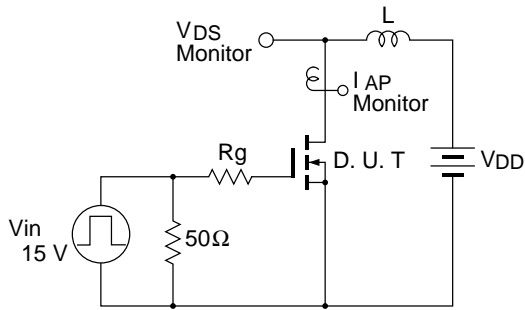
**2SK3082(L),2SK3082(S)**



# 2SK3082(L), 2SK3082(S)

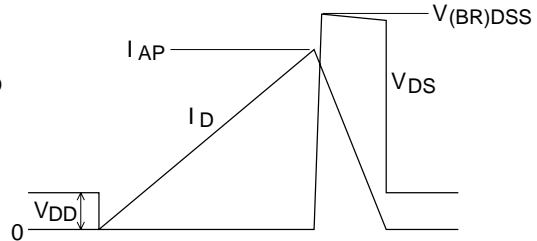


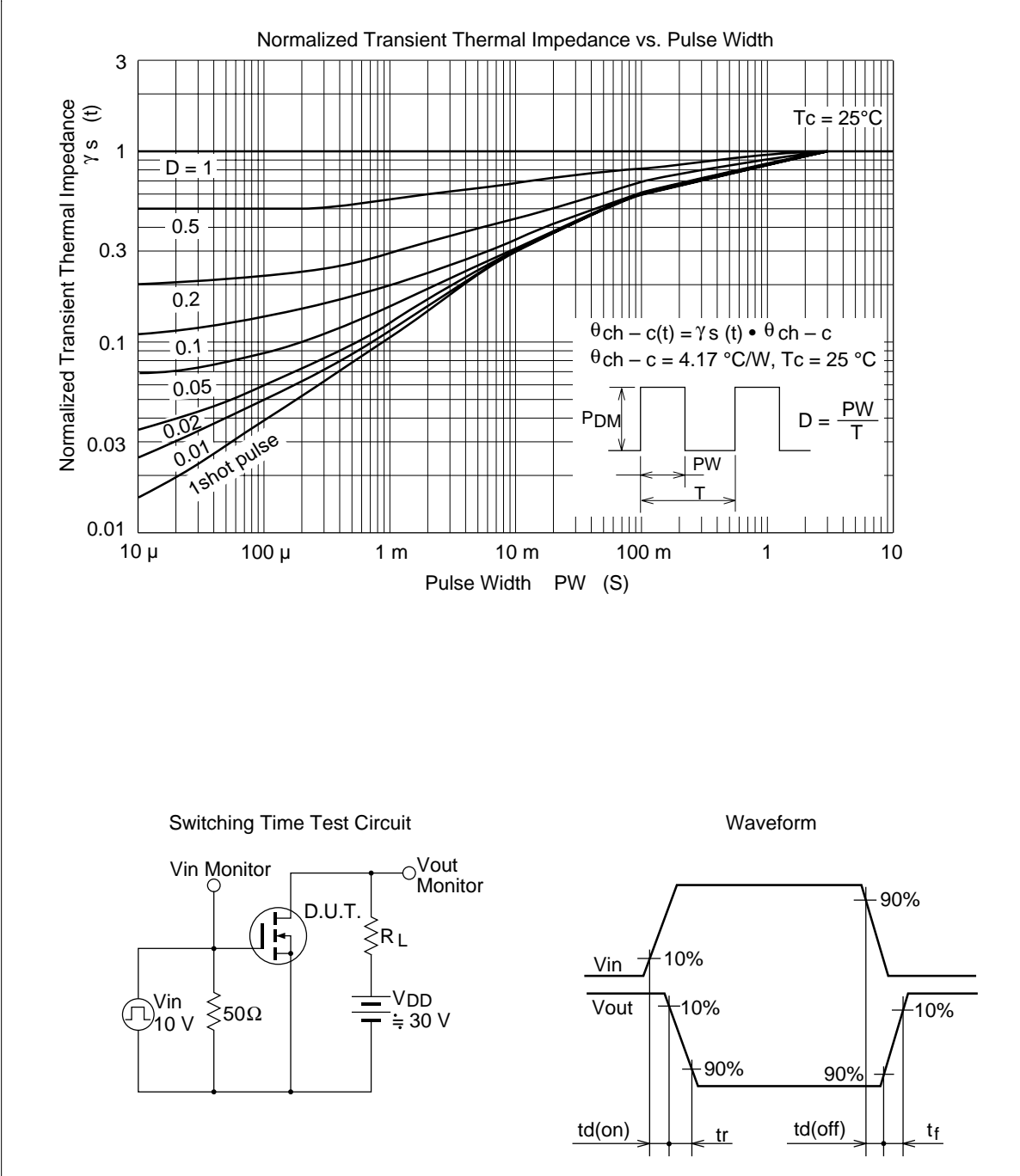
Avalanche Test Circuit



Avalanche Waveform

$$E_{AR} = \frac{1}{2} \cdot L \cdot I_{AP}^2 \cdot \frac{V_{DSS}}{V_{DSS} - V_{DD}}$$

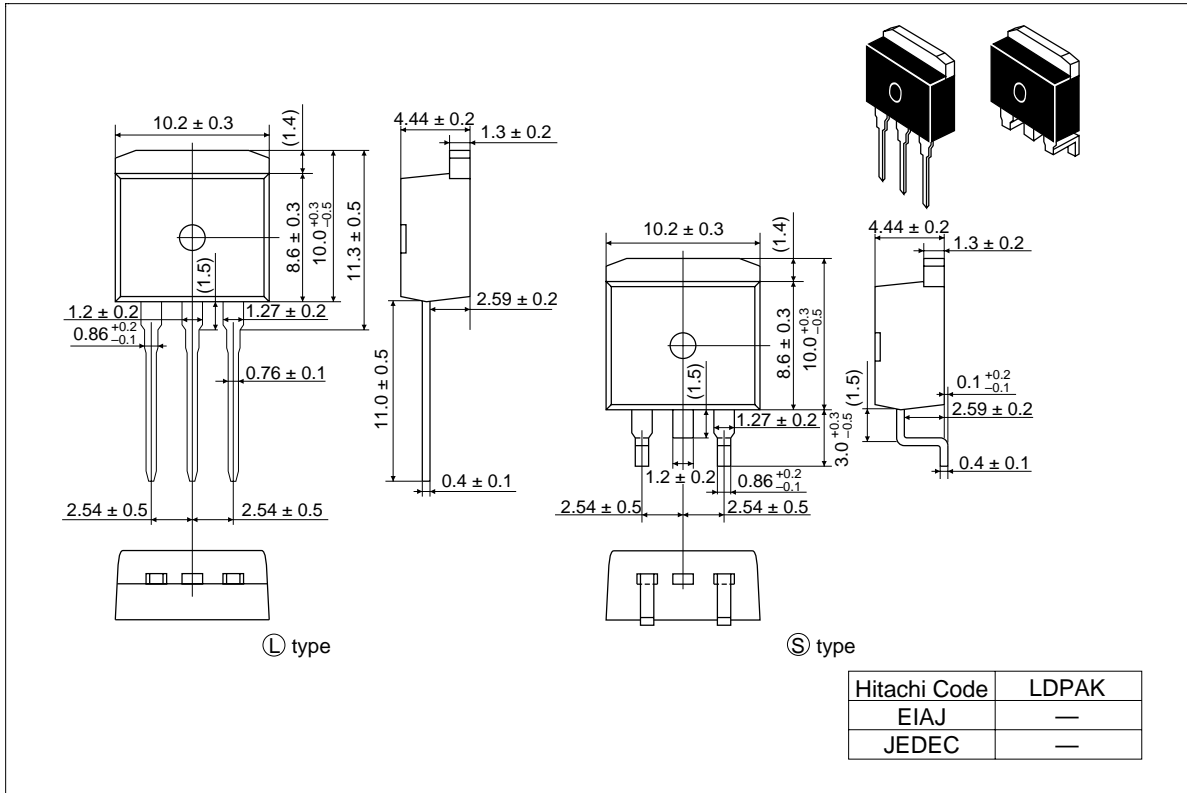




# 2SK3082(L),2SK3082(S)

## Package Dimensions

Unit: mm





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**HITACHI****Hitachi, Ltd.**

Semiconductor & IC Div.  
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan  
Tel: Tokyo (03) 3270-2111  
Fax: (03) 3270-5109

**For further information write to:**

Hitachi Semiconductor (America) Inc. 2000 Sierra Point Parkway Brisbane, CA. 94005-1897 U S A Tel: 800-285-1601 Fax: 303-297-0447	Hitachi Europe GmbH Continental Europe Dornacher Straße 3 D-85622 Feldkirchen München Tel: 089-9 91 80-0 Fax: 089-9 29 30-00	Hitachi Europe Ltd. Electronic Components Div. Northern Europe Headquarters Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA United Kingdom Tel: 01628-585000 Fax: 01628-585160	Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533	Hitachi Asia (Hong Kong) Ltd. Unit 706, North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon Hong Kong Tel: 27359218 Fax: 27306071
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